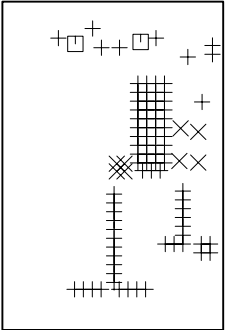


NOTES

MATERIAL: FR4 1 OZ COPPER EACH LAYER.
ALL HOLES PLATED THRU WITH 1 OZ COPPER MIN.
FINAL COPPER ON EXTERNAL LAYERS = 2 OZ. MINIMUM.

For best thermal performance,
Make GND copper as large as
possible, except on layer 1
directly under U1.

All spacings have been set
according to common PCB fabrication
and assembly practices. If necessary,
these spacings can be modified according to
customer manufacturing capabilities.



EV1380QI OPTIMUM PERFORMANCE SOLUTION

This layout shows the critical components
and traces for minimum footprint with ENABLE
tied to Vin. Alternate ENABLE configurations, & other small
signals should be routed according to specific application.

Solder mask and paste layer openings should be
reviewed and optimized to meet customer
PCB fabrication and assembly guidelines.

SIZE	QTY	SYM	PLATED	TOL
8	84	+	YES	*NOTE
5	8	×	YES	STD
16	2	□	YES	STD

*NOTE: USE 13 MIL DRILL FOR 8 MIL PLTD HOLES.
PLUGGING/FILLING OF 5mil and 8mil HOLES IS ACCEPTABLE.